

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TMCS1127A1AQDVGR	ACTIVE	SOIC	DVG	10	2000	RoHS & Green	SN	Level-2-260C-1 YEAR	-40 to 125	1127A1A	Samples
TMCS1127A2AQDVGR	ACTIVE	SOIC	DVG	10	2000	RoHS & Green	SN	Level-2-260C-1 YEAR	-40 to 125	1127A2A	Samples
TMCS1127A3AQDVGR	ACTIVE	SOIC	DVG	10	2000	RoHS & Green	SN	Level-2-260C-1 YEAR	-40 to 125	1127A3A	Samples
TMCS1127A4AQDVGR	ACTIVE	SOIC	DVG	10	2000	RoHS & Green	SN	Level-2-260C-1 YEAR	-40 to 125	1127A4A	Samples
TMCS1127A5AQDVGR	ACTIVE	SOIC	DVG	10	2000	RoHS & Green	SN	Level-2-260C-1 YEAR	-40 to 125	1127A5A	Samples
TMCS1127A6AQDVGR	ACTIVE	SOIC	DVG	10	2000	RoHS & Green	SN	Level-2-260C-1 YEAR	-40 to 125	1127A6A	Samples
TMCS1127B1AQDVGR	ACTIVE	SOIC	DVG	10	2000	RoHS & Green	SN	Level-2-260C-1 YEAR	-40 to 125	1127B1A	Samples
TMCS1127B2AQDVGR	ACTIVE	SOIC	DVG	10	2000	RoHS & Green	SN	Level-2-260C-1 YEAR	-40 to 125	1127B2A	Samples
TMCS1127B3AQDVGR	ACTIVE	SOIC	DVG	10	2000	RoHS & Green	SN	Level-2-260C-1 YEAR	-40 to 125	1127B3A	Samples
TMCS1127B4AQDVGR	ACTIVE	SOIC	DVG	10	2000	RoHS & Green	SN	Level-2-260C-1 YEAR	-40 to 125	1127B4A	Samples
TMCS1127B5AQDVGR	ACTIVE	SOIC	DVG	10	2000	RoHS & Green	SN	Level-2-260C-1 YEAR	-40 to 125	1127B5A	Samples
TMCS1127C1AQDVGR	ACTIVE	SOIC	DVG	10	2000	RoHS & Green	SN	Level-2-260C-1 YEAR	-40 to 125	1127C1A	Samples
TMCS1127C2AQDVGR	ACTIVE	SOIC	DVG	10	2000	RoHS & Green	SN	Level-2-260C-1 YEAR	-40 to 125	1127C2A	Samples
TMCS1127C3AQDVGR	ACTIVE	SOIC	DVG	10	2000	RoHS & Green	SN	Level-2-260C-1 YEAR	-40 to 125	1127C3A	Samples
TMCS1127C4AQDVGR	ACTIVE	SOIC	DVG	10	2000	RoHS & Green	SN	Level-2-260C-1 YEAR	-40 to 125	1127C4A	Samples
TMCS1127C5AQDVGR	ACTIVE	SOIC	DVG	10	2000	RoHS & Green	SN	Level-2-260C-1 YEAR	-40 to 125	1127C5A	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of ≤ 1000 ppm threshold. Antimony trioxide based flame retardants must also meet the ≤ 1000 ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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